

SLOVENSKI STANDARD
SIST EN IEC 61189-2-803:2023
01-november-2023

Preskusne metode za električne materiale, tiskana vezja in druge povezovalne strukture in sestave - 2-803. del: Metode za preskušanje raztezanja po osi Z tankih podložnih materialov

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-803: Test methods for Z-Axis Expansion of base materials and printed board

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen – Teil 2-803: Prüfverfahren für die Z-Achsen-Ausdehnung von Basismaterialien und Leiterplatten

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-803: Méthodes d'essai pour la dilatation suivant l'axe Z des matériaux de base et des cartes imprimées

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Ta slovenski standard je istoveten z: EN IEC 61189-2-803:2023

ICS:

31.180 Tiskana vezja (TIV) in tiskane Printed circuits and boards
 plošče

SIST EN IEC 61189-2-803:2023 en

**EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM**

EN IEC 61189-2-803

September 2023

ICS 31.180

English Version

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-803: Test methods for Z-axis expansion of base materials and printed boards
(IEC 61189-2-803:2023)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-803: Méthodes d'essai pour la dilatation suivant l'axe Z des matériaux de base et des cartes imprimées
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Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 2-803: Prüfverfahren für die Z-Achsen-Ausdehnung von Basismaterialien und Leiterplatten
(IEC 61189-2-803:2023)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.
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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61189-2-803:2023 (E)**European foreword**

The text of document 91/1760/CDV, future edition 1 of IEC 61189-2-803, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-803:2023.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2024-05-30 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2026-08-30 document have to be withdrawn

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Endorsement notice

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-1	-	Printed boards design, manufacture and assembly - Vocabulary - Part 1: Common usage in printed board and electronic assembly technologies	-	-

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